

Claims

- [c1] 11. A semiconductor circuit component comprising a circuit die, said circuit die having at least one electrical contact area for connection to the packaging of said semiconductor circuit component, said at least one electrical contact area being bond to the corresponding lead of said packaging by metallic material formed by a metal ball of prescribed feed melted during the fabrication of said component.
- [c2] 12. The semiconductor circuit component of claim 11, wherein said metal ball contains copper.
- [c3] 13. The semiconductor circuit component of claim 11 wherein said metal ball contains aluminum.
- [c4] 14. The semiconductor circuit component of claim 11, wherein said metal ball contains tin.
- [c5] 15. The semiconductor circuit component of claim 11, wherein said metal ball contains lead.
- [c6] 16. The semiconductor circuit component of claim 11, further comprising a second metal bump.

- [c7] 17. The semiconductor circuit component of claim 16, wherein said two metal bumps being of different sizes.
- [c8] 18. The semiconductor circuit component of claim 16, wherein said two metal bumps being of different shapes.
- [c9] 19. The semiconductor circuit component of claim 16, wherein said two metal bumps being made of different materials.
- [c10] 20. The semiconductor circuit component of claim 11, further comprising at least one more metal bump.